
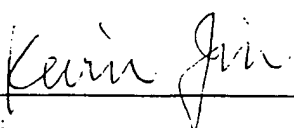
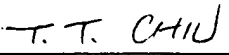


PAGE 1 OF 1

APPLICATION FOR UNITED STATES PATENT **DECLARATION AND POWER OF ATTORNEY**

As a below named inventor, I declare that my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor if only one name is listed below, or an original, first and joint inventor if plural inventors are named below, of the subject matter which is claimed and for which a patent is sought on the invention entitled as set forth below, which is described in the attached specification of Application Serial No. 10/032,907, filed 12/28/01; that I have reviewed and understand the contents of the specification, including the claims, as amended by any amendment specifically referred to in the oath or declaration; that no application for patent or inventor's certificate on this invention has been filed by me or my legal representatives or assigns in any country foreign to the United States of America; and that I acknowledge my duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, Section 1.56;

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

TITLE OF INVENTION:		
Method and Apparatus for Flip Chip Device Assembly by Radiant Heating		
POWER OF ATTORNEY: I HEREBY APPOINT PRACTITIONERS AT CUSTOMER NUMBER 23494 TO PROSECUTE THIS APPLICATION AND TRANSACT ALL BUSINESS IN THE PATENT AND TRADEMARK OFFICE CONNECTED THEREWITH		
SEND CORRESPONDENCE TO: Gary C. Honeycutt Texas Instruments Incorporated P.O. Box 655474, MS 3999 Dallas, TX 75265		DIRECT TELEPHONE CALLS TO: Gary C. Honeycutt (972) 238-7160
NAME OF INVENTOR: (1) Jimmy Liang	NAME OF INVENTOR: (2) Kevin Jin	NAME OF INVENTOR: (3) T.T. Chiu
RESIDENCE & POST OFFICE ADDRESS: 2 nd Floor, #14-17, I-chen street, Nan-Kong area Taipei City, Taiwan	RESIDENCE & POST OFFICE ADDRESS: 5F, 25, Chien-Hsing St. Hsin-Tien City, Taipei, Taiwan	RESIDENCE & POST OFFICE ADDRESS: 4F, 16, Lane 7, Sec 2, Shiue Fu Rd. Tu Cheng City, Taipei, Taiwan
COUNTRY OF CITIZENSHIP: Taiwan, R.O.C.	COUNTRY OF CITIZENSHIP: Taiwan, R.O.C.	COUNTRY OF CITIZENSHIP: Taiwan, R.O.C.
SIGNATURE OF INVENTOR: x 	SIGNATURE OF INVENTOR: x 	SIGNATURE OF INVENTOR: x 
DATE: x Jan. 21, 2002	DATE: x Jan. 30, 2002	DATE: x Jan, 30, 2002



666

MAY 21, 2002

PTAS

Chief Information Officer
Washington, DC 20231
www.uspto.gov

TEXAS INSTRUMENTS INCORPORATED
GARY C. HONEYCUTT
P.O. BOX 655474, MS 3999
DALLAS, TX 75265



102036455A

UNITED STATES PATENT AND TRADEMARK OFFICE
NOTICE OF RECORDATION OF ASSIGNMENT DOCUMENT

THE ENCLOSED DOCUMENT HAS BEEN RECORDED BY THE ASSIGNMENT DIVISION OF THE U.S. PATENT AND TRADEMARK OFFICE. A COMPLETE MICROFILM COPY IS AVAILABLE AT THE ASSIGNMENT SEARCH ROOM ON THE REEL AND FRAME NUMBER REFERENCED BELOW.

PLEASE REVIEW ALL INFORMATION CONTAINED ON THIS NOTICE. THE INFORMATION CONTAINED ON THIS RECORDATION NOTICE REFLECTS THE DATA PRESENT IN THE PATENT AND TRADEMARK ASSIGNMENT SYSTEM. IF YOU SHOULD FIND ANY ERRORS OR HAVE QUESTIONS CONCERNING THIS NOTICE, YOU MAY CONTACT THE EMPLOYEE WHOSE NAME APPEARS ON THIS NOTICE AT 703-308-9723. PLEASE SEND REQUEST FOR CORRECTION TO: U.S. PATENT AND TRADEMARK OFFICE, ASSIGNMENT DIVISION, BOX ASSIGNMENTS, CG-4, 1213 JEFFERSON DAVIS HWY, SUITE 320, WASHINGTON, D.C. 20231.

RECORDATION DATE: 03/21/2002

REEL/FRAME: 012717/0264
NUMBER OF PAGES: 2

BRIEF: ASSIGNMENT OF ASSIGNOR'S INTEREST (SEE DOCUMENT FOR DETAILS).

ASSIGNOR:
LIANG, JIMMY

DOC DATE: 01/21/2002

ASSIGNOR:
JIN, KEVIN

DOC DATE: 01/30/2002

ASSIGNOR:
CHIU, T.T.

DOC DATE: 01/30/2002

ASSIGNEE:
TEXAS INSTRUMENTS INCORPORATED
P.O. BOX 655474, MS 3999
DALLAS, TEXAS 75265

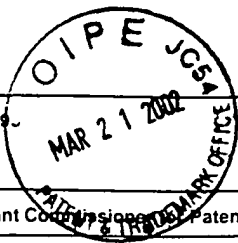
SERIAL NUMBER: 10032907
PATENT NUMBER:

FILING DATE: 12/28/2001
ISSUE DATE:

15

012717/0264 PAGE 2

MAURICE CARTER, EXAMINER
ASSIGNMENT DIVISION
OFFICE OF PUBLIC RECORDS



03-29-2002



FORM PT -159

U.S. Department of Commerce
Patent and Trademark Office

TI-32508

102036455

To the Assistant Commissioner of Patents. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Jimmy Liang 1/21/02
Kevin Jin 1/30/02
T.T. Chiu 1/30/02

3-21-02

2. Name and Address of receiving party(ies):

Name: TEXAS INSTRUMENTS INCORPORATED

Address: P.O. Box 655474, MS 3999

City: Dallas

State: TX Zip: 75265

Additional name(s) & address(es) attached? ___ Yes ___X___ No

3. Nature of Conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date in order of listed parties: 1/21/02; 1/30/02; 1/30/02

4. Application number(s) or patent number(s).

☐ This document is being filed together with a new application.

Execution date of the application in order of listed parties: 1/21/02; 1/30/02; 1/30/02

Title: Method and Apparatus for Flip Chip Device Assembly by Radian Heating

Docket No: TI-32508

A. Patent Application No.(s)

S.N. 10/032,907

B. Patent No.(s)

X,XXX,XXX

Additional numbers attached? ___ Yes ___X___ No

Additional numbers attached? ___ Yes ___X___ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Gary C. Honeycutt
Texas Instruments Incorporated

Address: P.O. Box 655474, MS 3999

City: Dallas

State: TX Zip: 75265

6. Number of applications and patents involved: ___(1)___

7. Amount of fee enclosed or authorized to be charged: \$40

8. Deposit Account No: 20-0668 (Attach duplicate copy if paying by deposit account)

03/28/2002 DBYRNE 00000273 200668 10032907

01 FC-561 40.00 CH

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date

3/8/02

Gary C. Honeycutt, Reg. No. 20250

Total Number of Pages Including Cover Sheet, Attachments and Document: 2

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

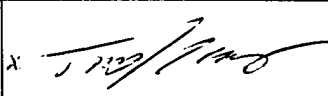
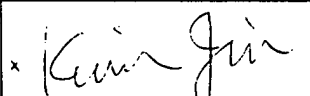
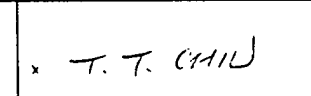
WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 7839 Churchill Way, MS 3999, Dallas, Texas 75251, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE OF INVENTION	Method and Apparatus for Flip Chip Device Assembly by Radiant Heating		
SIGNATURE OF INVENTOR AND NAME	x  Jimmy Liang	x  Kevin Jin	x  T.T. Chiu
DATE OF SIGNATURE	x Jan. 21 2002	x Jan. 20 2002	x Jan. 30, 2002
RESIDENCE (City, State)	Taipei, Taiwan	Taipei, Taiwan	Taipei, Taiwan
DATE APPLICATION EXECUTED			

After recording Assignment, please return to:

Gary C. Honeycutt
Texas Instruments Incorporated
P.O. Box 655474, MS 3999
Dallas, TX 75265